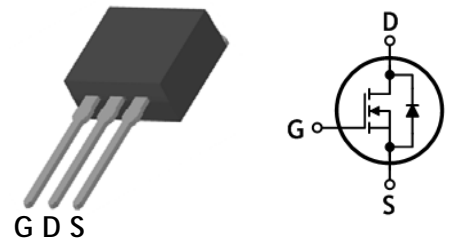


## HIGH SPEED SWITCHING APPLICATION

### Features

- Low drain-source On resistance:  $R_{DS(on)}=1.1\Omega$  (Typ.)
- Low gate charge:  $Q_g=18nC$  (Typ.)
- Low reverse transfer capacitance:  $C_{rss}=5.5pF$  (Typ.)
- RoHS compliant device
- 100% avalanche tested

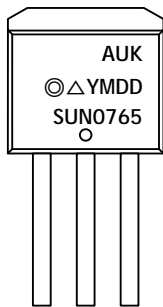


### Ordering Information

Part Number	Marking	Package
SUN0765I2	SUN0765	I2-PAK

**I2-PAK**

### Marking Information



Column 1: Manufacturer  
 Column 2: Production Information  
 e.g.) ◎△YMDD  
 -. ◎: Option Code (H: Halogen Free)  
 -. △: Factory Management Code  
 -. YMDD: Date Code (Year, Month, Date)  
 Column 3: Device Code

### Absolute maximum ratings ( $T_c=25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Rating	Unit	
Drain-source voltage	$V_{DSS}$	650	V	
Gate-source voltage	$V_{GSS}$	±30	V	
Drain current (DC) *	$I_D$	$T_c=25^\circ C$	7	A
		$T_c=100^\circ C$	4.43	A
Drain current (Pulsed) *	$I_{DM}$	28	A	
Single avalanche energy <sup>(Note 2)</sup>	$E_{AS}$	92.9	mJ	
Repetitive avalanche current <sup>(Note 1)</sup>	$I_{AR}$	7	A	
Repetitive avalanche energy <sup>(Note 1)</sup>	$E_{AR}$	11	mJ	
Power dissipation	$P_D$	110	W	
Junction temperature	$T_J$	150	°C	
Storage temperature range	$T_{stg}$	-55~150	°C	

\* Limited only maximum junction temperature

## Thermal Characteristics

Characteristic	Symbol	Rating	Unit
Thermal resistance, junction to case	$R_{th(j-c)}$	Max. 1.13	°C/W
Thermal resistance, junction to ambient	$R_{th(j-a)}$	Max. 50	

Electrical Characteristics ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	$BV_{DSS}$	$I_D=250\mu\text{A}$ , $V_{GS}=0$	650	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu\text{A}$ , $V_{DS}=V_{GS}$	3	-	5	V
Drain-source cut-off current	$I_{DSS}$	$V_{DS}=650\text{V}$ , $V_{GS}=0\text{V}$	-	-	1	$\mu\text{A}$
		$V_{DS}=650\text{V}$ , $T_C=150^\circ\text{C}$	-	-	100	$\mu\text{A}$
Gate leakage current	$I_{GSS}$	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 30\text{V}$	-	-	$\pm 100$	nA
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}$ , $I_D=3.5\text{A}$	-	1.1	1.4	$\Omega$
Forward transfer conductance (Note 3)	$g_{fs}$	$V_{DS}=10\text{V}$ , $I_D=3.5\text{A}$	-	8.7	-	S
Input capacitance	$C_{iss}$	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	1385	-	pF
Output capacitance	$C_{oss}$		-	102	-	
Reverse transfer capacitance	$C_{rss}$		-	5.5	-	
Turn-on delay time (Note 3,4)	$t_{d(on)}$	$V_{DS}=325\text{V}$ , $I_D=7\text{A}$ , $R_G=25\Omega$	-	60	-	ns
Rise time (Note 3,4)	$t_r$		-	32	-	
Turn-off delay time (Note 3,4)	$t_{d(off)}$		-	113	-	
Fall time (Note 3,4)	$t_f$		-	22	-	
Total gate charge (Note 3,4)	$Q_g$	$V_{DS}=520\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=7\text{A}$	-	18	23	nC
Gate-source charge (Note 3,4)	$Q_{gs}$		-	7	-	
Gate-drain charge (Note 3,4)	$Q_{gd}$		-	3	-	

Source-Drain Diode Ratings and Characteristics ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	$I_S$	Integral reverse diode in the MOSFET	-	-	7	A
Source current (Pulsed)	$I_{SM}$		-	-	28	A
Forward voltage	$V_{SD}$	$V_{GS}=0\text{V}$ , $I_{SD}=7\text{A}$	-	-	1.4	V
Reverse recovery time (Note 3,4)	$t_{rr}$	$I_{SD}=7\text{A}$ , $V_{GS}=0\text{V}$ $di_F/dt=100\text{A}/\mu\text{s}$	-	410	-	ns
Reverse recovery charge (Note 3,4)	$Q_{rr}$		-	1.7	-	$\mu\text{C}$

Note:

1. Repeated rating: Pulse width limited by safe operating area
2.  $L=3.5\text{mH}$ ,  $I_{AS}=7\text{A}$ ,  $V_{DD}=50\text{V}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3. Pulse test: Pulse width $\leq 300\mu\text{s}$ , Duty cycle $\leq 2\%$
4. Essentially independent of operating temperature typical characteristics

Typical Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

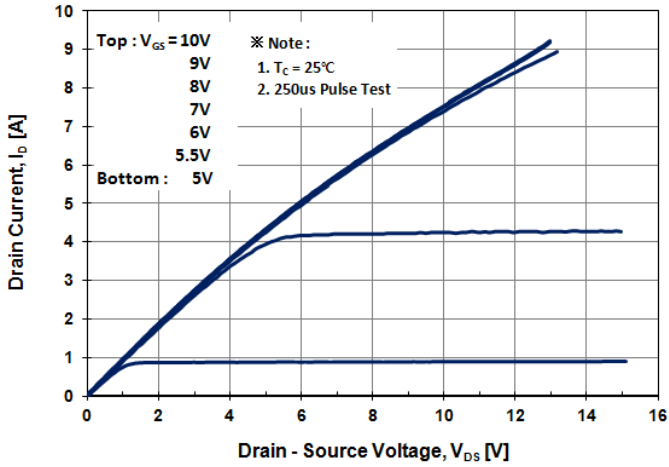


Fig. 2 Typical Output Characteristics

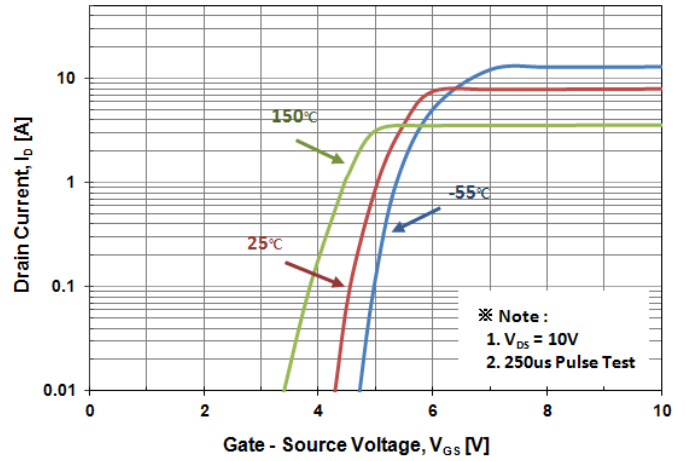


Fig.3 On-Resistance Variation with Drain Current and Gate Voltage

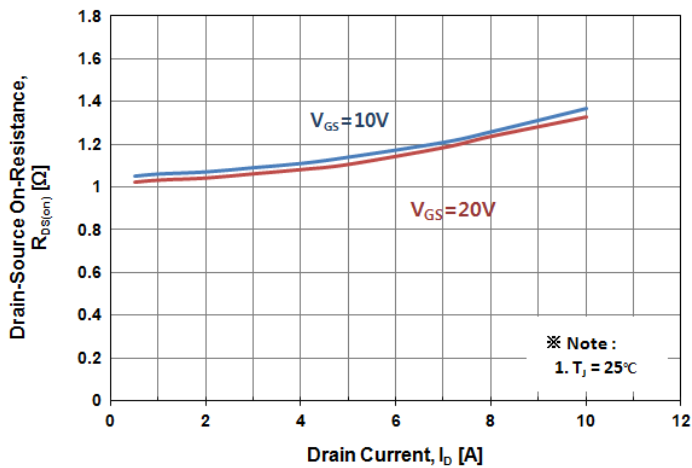


Fig. 4 Body Diode Forward Voltage Variation with Source Current

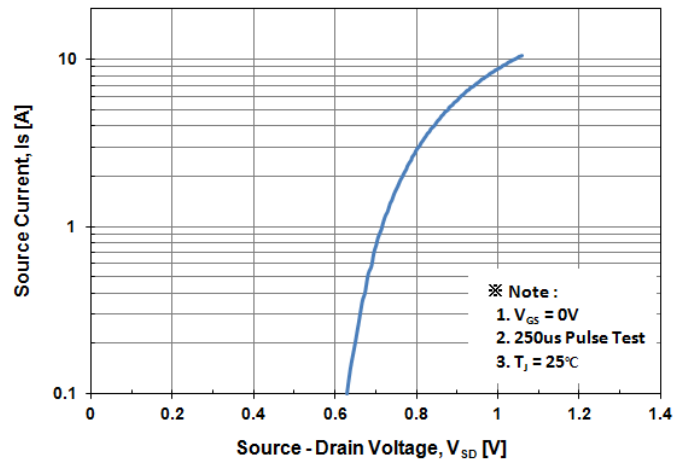


Fig. 5 Typical Capacitance Characteristics

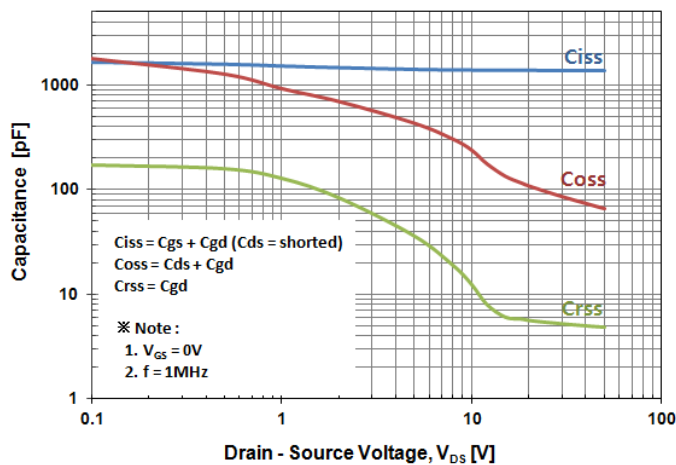


Fig. 6 Typical Total Gate Charge Characteristics

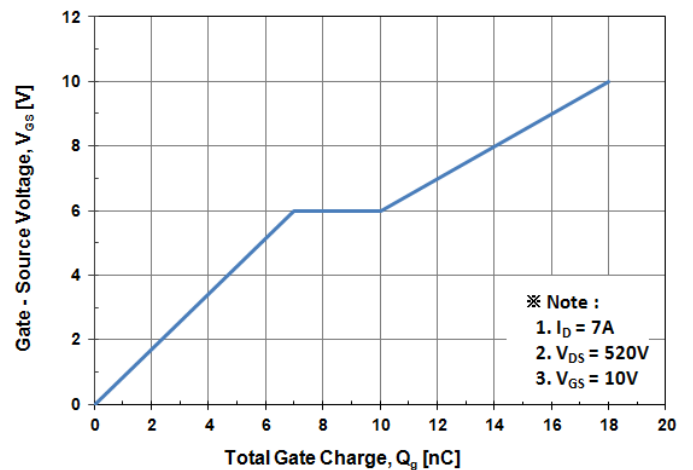


Fig. 7 Breakdown Voltage Variation vs. Temperature

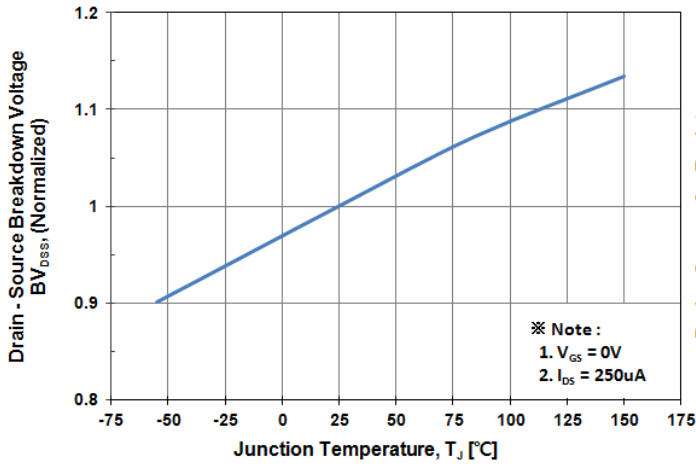


Fig. 8 On-Resistance Variation vs. Temperature

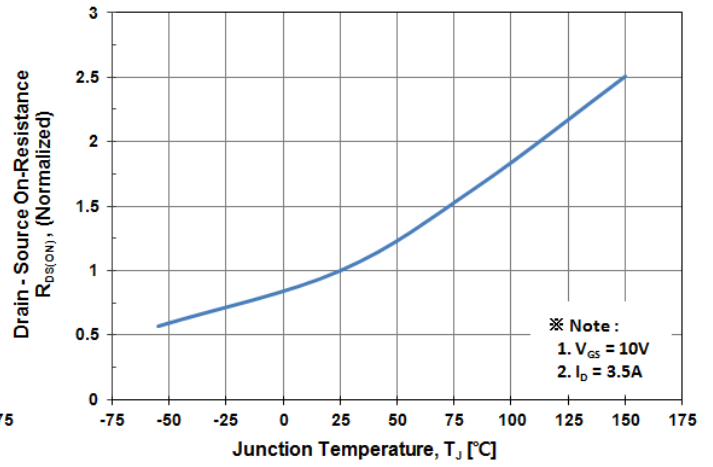


Fig. 9 Maximum Drain Current vs. Case Temperature

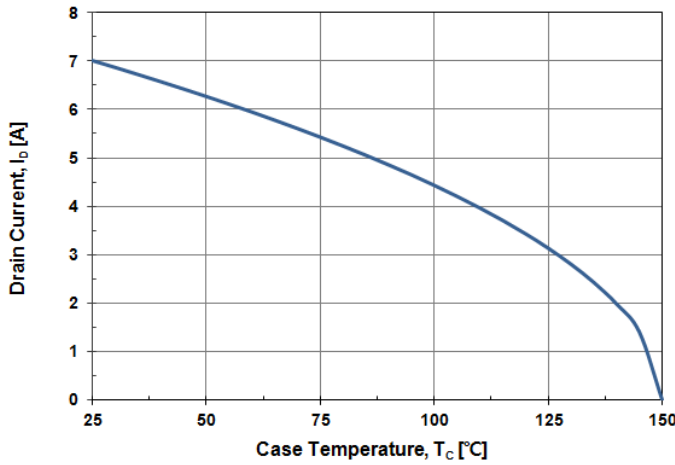


Fig. 10 Maximum Safe Operating Area

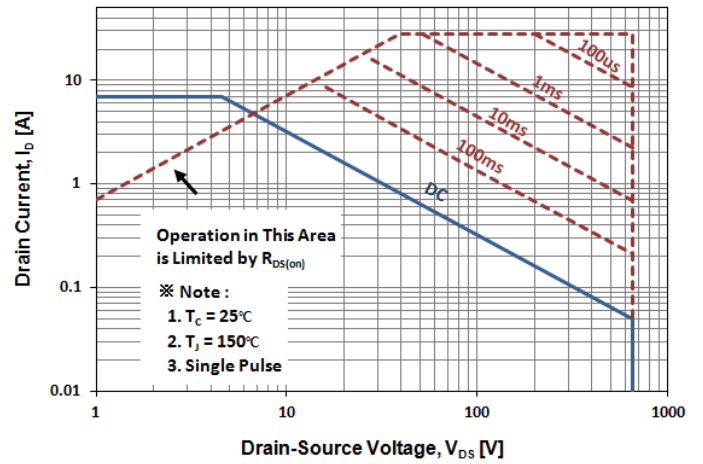


Fig. 11 Transient Thermal Impedance

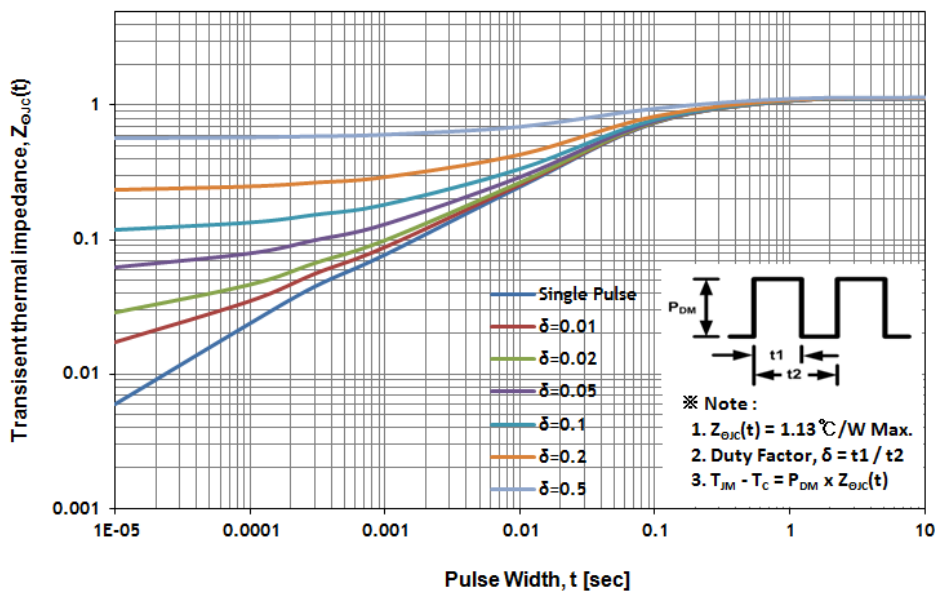


Fig. 12 Gate Charge Test Circuit & Waveform

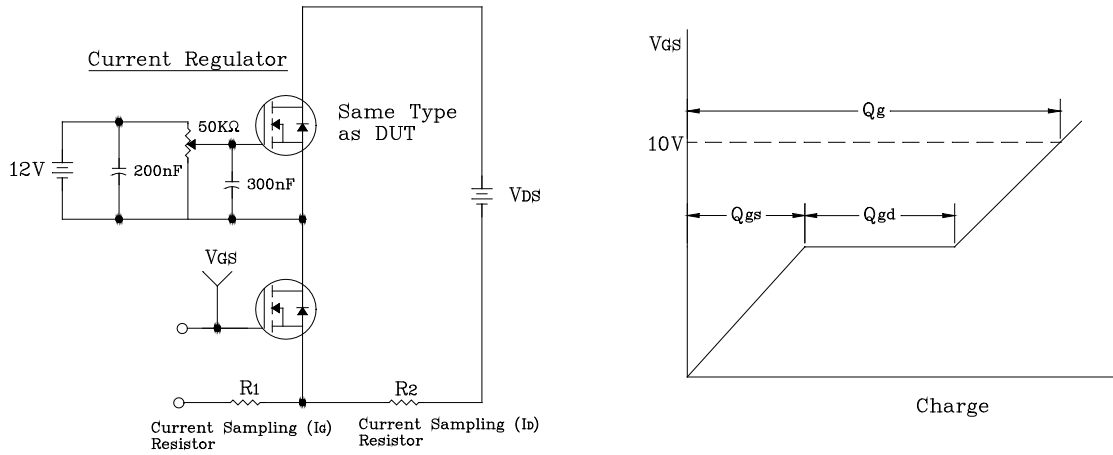


Fig. 13 Resistive Switching Test Circuit & Waveform

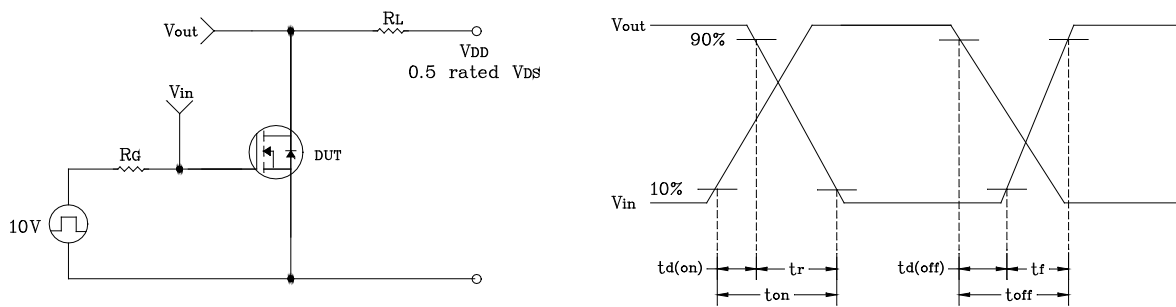


Fig. 14  $E_{AS}$  Test Circuit & Waveform

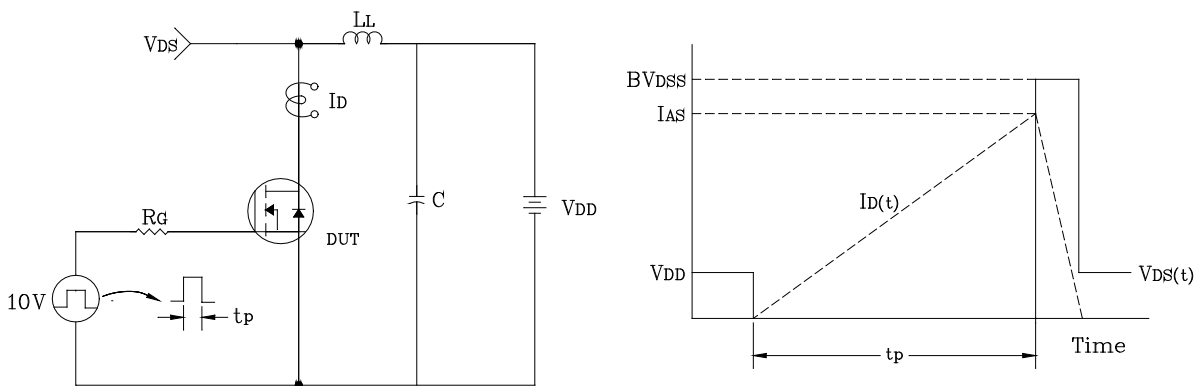
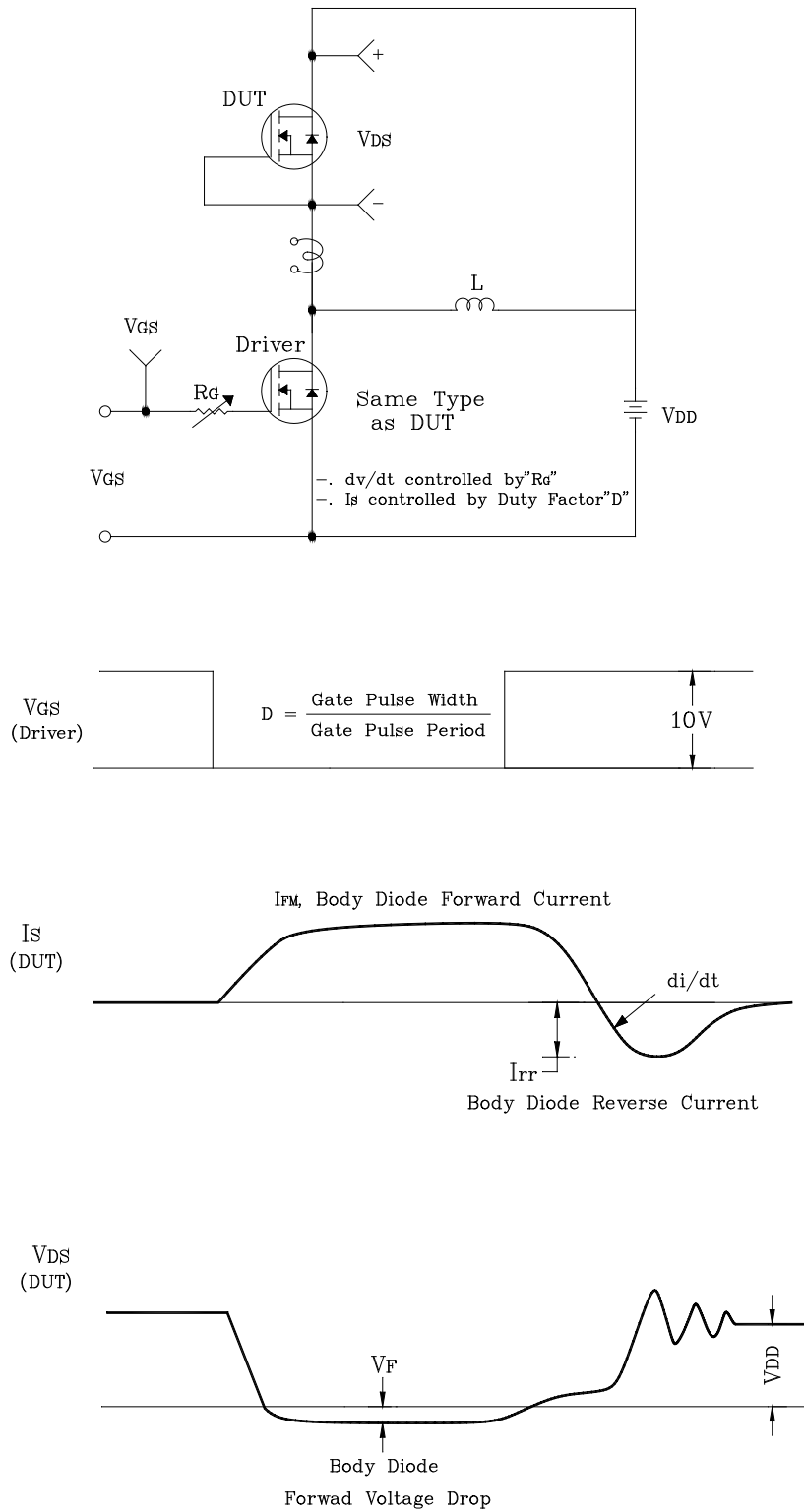
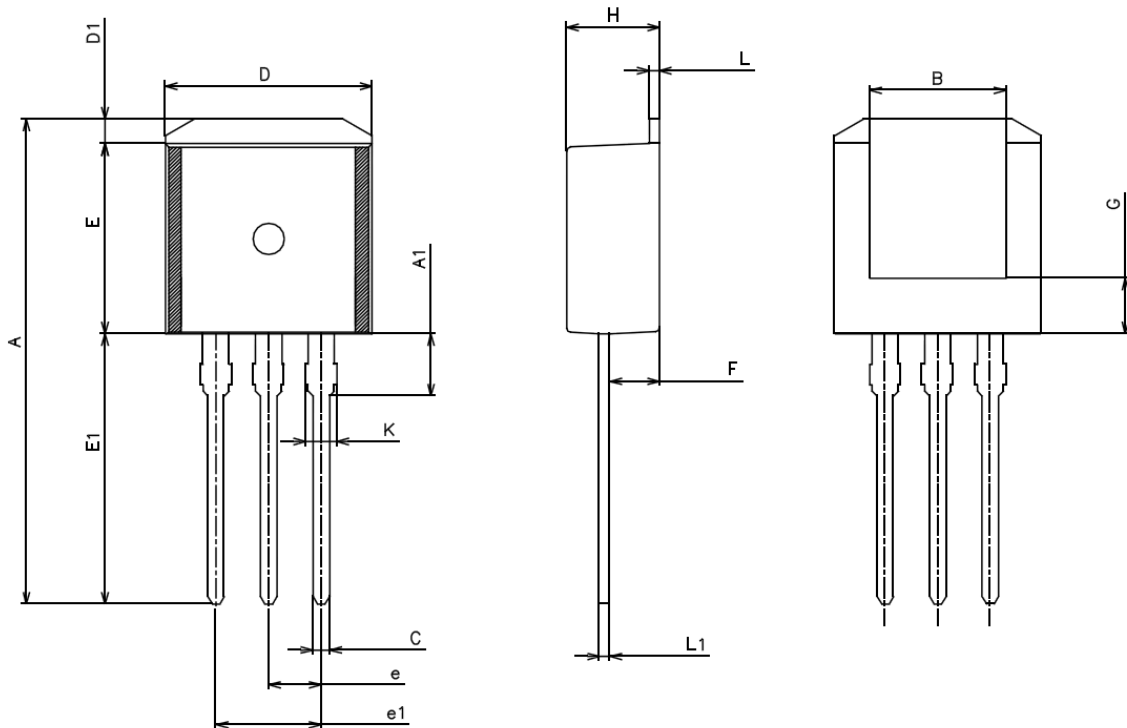


Fig. 15 Diode Reverse Recovery Time Test Circuit & Waveform



Package Outline Dimensions



SYMBOL	MILLIMETERS			NOTE
	MINIMUM	NOMINAL	MAXIMUM	
A	22.98	23.48	23.98	
A1	2.80	3.00	3.20	
B	6.40	6.60	6.80	
C	0.60	0.80	1.00	
D	9.80	10.00	10.20	
D1	1.00	1.20	1.40	
E	9.05	9.20	9.35	
E1	12.68	13.08	13.48	
e	2.34	2.54	2.74	
e1	4.88	5.08	5.28	
F	2.20	2.40	2.60	
G	2.50	2.70	2.90	
H	4.35	4.50	4.65	
K	1.42	1.52	1.62	
L	0.40	0.50	0.60	
L1	0.40	0.50	0.60	

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